

Amendments to the Specification:

Please amend the specification as follows:

Please replace the first paragraph starting at page 8, after Detailed Description of the Preferred Embodiments, with the following rewritten paragraph:

Fig. 1 is a perspective view showing the constitution of a substrate processing system according to an embodiment of the present invention. As Fig. 1 shows, a substrate processing apparatus 2, which is an apparatus for semiconductor manufacturing equipment, substrate cleaning equipment, is provided with a load port table 2a in the front thereof to once stop the FOUP 1 that has been conveyed, opens and closes the carrier door of the FOUP 1 and the load port door 12 of the substrate processing apparatus 2, and brings wafers in and out of the substrate processing apparatus 2. The load port table 2a specified in the above-described SEMI Standards is a load port table having an FIMS surface. Here, FIMS is the abbreviation of the "front-opening interface mechanical standard." In Fig. 1, the constituting components common to those in Fig. 2 are denominated by the same reference numerals and characters as in Fig. 2.

Please replace the second paragraph starting at page 9, with the following rewritten paragraph:

On the front and the side of the load port table 2a, a second falling prevention cover (shield plate) 6 is provided upward up to the location immediately under the OHT 3. On the front of the second falling prevention cover 6, a front door 7 is provided. The second falling prevention cover 6 disposed on the side of the load port table 2a is connected to the first falling prevention cover 4 immediately under the OHT 3. In Fig. 1, since the rear side of the load port table 2a is a region for actually bringing wafer in and out through the load port door 12, by disposing the second falling prevention cover 6 on the front and the side of the load port table 2a, the load port table 2a is completely surrounded by the second falling prevention cover 6.